

Search notes

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	180	438/50.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 14:50
L4	289	438/51.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 15:14
L6	185	438/52.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 15:30
L7	143	438/53.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 15:52
L8	2207	(mems or cantilever or membrane or diaphragm or microstructure) and (plasma) near5 (etch or etchant or etching or etched or rie) near10 (sacrificial or dummy or undercut\$3 or under or floating or tunnel or photoresist or resist or resin or epoxy or polyimide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 15:55
L10	503	(mems or cantilever or membrane or diaphragm or microstructure) and (oxygen or o!) near2 (plasma) near8 (etch or etchant or etching or etched or rie) near10 (sacrificial or dummy or undercut\$3 or under or floating or tunnel or photoresist or resist or resin or epoxy or polyimide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 15:56
L12	76	(mems! or cantilever or membrane or diaphragm or microstructure) same (oxygen or o!) near2 (plasma) near8 (etch or etchant or etching or etched or rie) near10 (sacrificial or dummy or undercut\$3 or under or floating or tunnel or photoresist or resist or resin or epoxy or polyimide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 16:09
L13	8	(mems! or microelectromechanical or microstructure or cantilever) same (undercut\$4 or under-cut\$4 or under-etch\$4) near4 (plasma)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 16:11
L14	85	(mems! or microelectromechanical or microstructure or micro-electro-mechanical) same (cantilever) near8 (etch\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 16:27
L15	24	(mems! or microelectromechanical or microstructure or micro-electro-mechanical) same (cantilever or membrane or overhang\$4) near8 (plasma)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 16:38
L16	25	(mems! or microelectromechanical or microstructure or micro-electro-mechanical) same (cantilever or membrane or overhang\$4) near8 (photoresist or resist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 16:42
L17	1528	(mems! or microelectromechanical or microstructure or micro-electro-mechanical or cantilever) and (etch\$4) near5 (undercut\$4 or under-cut\$4 or overhang\$4 or over-hang\$4 or void or tunnel or air near gap or air near bridge or (under or underneath or around or surrounding or below or beneath) near4 (cantilever))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 16:44

L18	388	(mems! or microelectromechanical or microstructure or micro-electro-mechanical or cantilever) and (etch\$4) near5 (undercut\$4 or under-cut\$4 or overhang\$4 or over-hang\$4 or void or tunnel or air near gap or air near bridge or (under or underneath or around or surrounding or below or beneath) near4 (cantilever)) near20 (photoresist or sacrificial or dummy or etch\$3 near selectiv\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 16:55
L20	20	"5573679".pn. "5578976".pn. "5834333".pn. "5493177".pn. "5083857".pn. "5314572".pn. "5493177".pn. "5683591".pn. "5798283".pn. "6238580".pn. "5285131".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 17:08
L21	202	(mems! or microelectromechanical or microstructure or micro-electro-mechanical or cantilever) near8 (sealed or sealing or seal or hermetic or airtight or air-tight or hermetically) near4 (cavity or pocket or volume)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 17:06
L23	18	"5573679".pn. "5578976".pn. "5834333".pn. "5493177".pn. "5083857".pn. "5314572".pn. "5493177".pn. "5683591".pn. "5798283".pn. "6238580".pn. "5285131".pn. and (plasma near4 oxygen) and aluminum and (photoresist near5 sacrificial)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 17:09

Interference Search

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L26	18	((mems! or microstructur\$3 or microelectromechanical or cantilever) and (sealed or hermetic or hermetically or cavity) and (plasma) near4 (etch\$4)).dm.	US-PGPUB	OR	ON	2005/08/11 17:12
L27	4	((mems! or microstructur\$3 or microelectromechanical or cantilever) and (sealed or hermetic or hermetically or cavity) and (plasma) near4 (oxygen or o!)).dm.	US-PGPUB	OR	ON	2005/08/11 17:13
L28	3	((mems! or microstructur\$3 or microelectromechanical or cantilever) and (sealed or hermetic or hermetically or cavity) and (sacrificial or dummy) near4 (photoresist or resist)).dm.	US-PGPUB	OR	ON	2005/08/11 17:14
L29	1	((mems! or microstructur\$3 or microelectromechanical or cantilever) and (sacrificial or dummy) near4 (photoresist or resist) and (oxygen or o) near (plasma)).dm.	US-PGPUB	OR	ON	2005/08/11 17:20
L30	0	((mems! or microstructur\$3 or microelectromechanical or cantilever) and (seal or sealed or cap or capped or hermetic) near5 (holes or apertures or openings) near5 plasma).dm.	US-PGPUB	OR	ON	2005/08/11 17:20